

# SEE Laser testing at ESA

Thomas Borel, Michele Muschitiello, Viyas Gupta, Marta Rizzo, Philipp Mand, Federico Reghenzani

ESA ESTEC

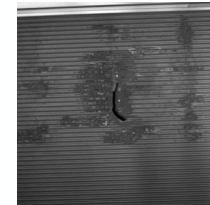
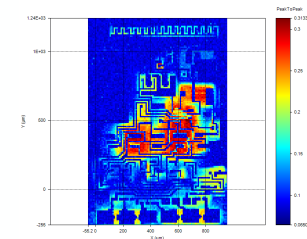
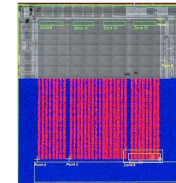
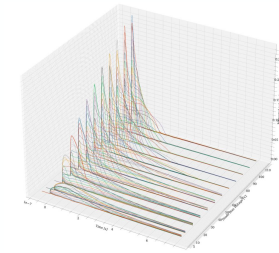
21/08/2024

## ESA Labs equipped since mid-2021

Several classical tests performed (Screening, cross section assessment, ... )

### Non-Routine test cases:

- Comparison SEE Laser vs Heavy Ions
  - Pin diode: Analysis of Pulse profile
  - SRAM: Comparison with SEL in-Flight Data
  - Voltage Reference: Assessment of Worst-Case SET
- Failure Analysis:
  - Point of Load: Localisation of SEFI and SEB
- Fault Injection
  - $\mu$ P STM32: Test of Software Protection Technics to SEU



# Comparison Heavy Ion / Laser

Case of a PIN Diode



**DUT:** Pin Diode

**Background:**

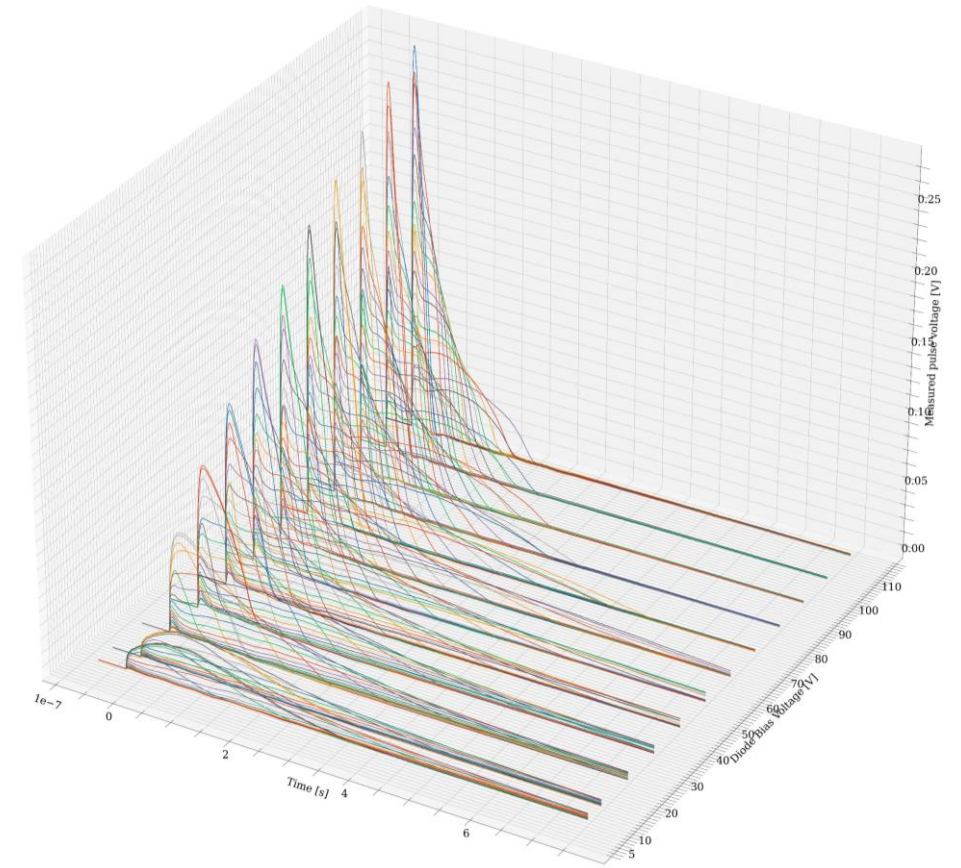
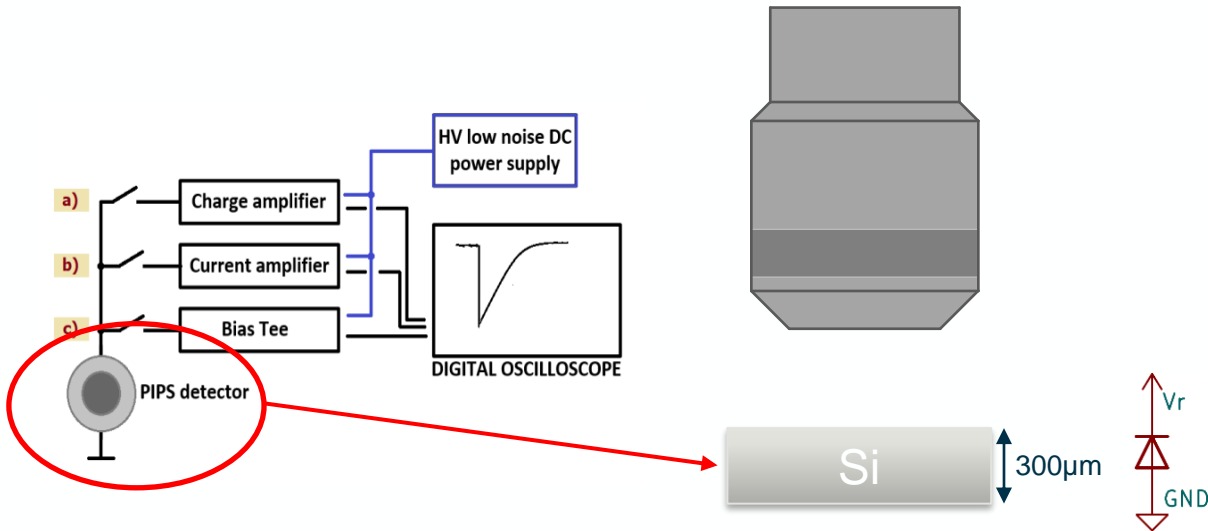
- System used by ESA for spectral characterisations of beam

T. Borel et al., "PIPS Diode Test Setup for Heavy Ion Beam Spectral Characterization," in IEEE Transactions on Nuclear Science, vol. 70, no. 8, pp. 1732-1739, Aug. 2023



**Objective:**

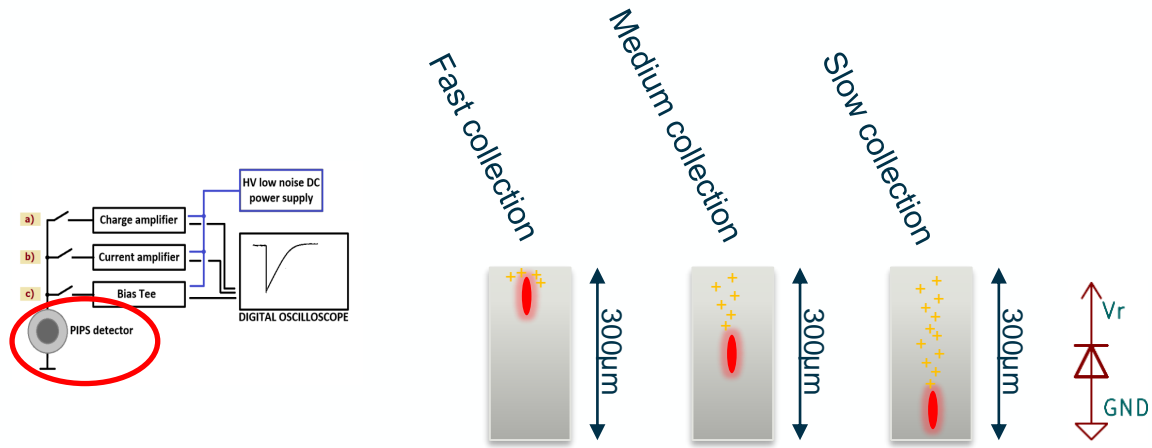
- Understanding better the charge deposition mechanism by analysing pulse shapes



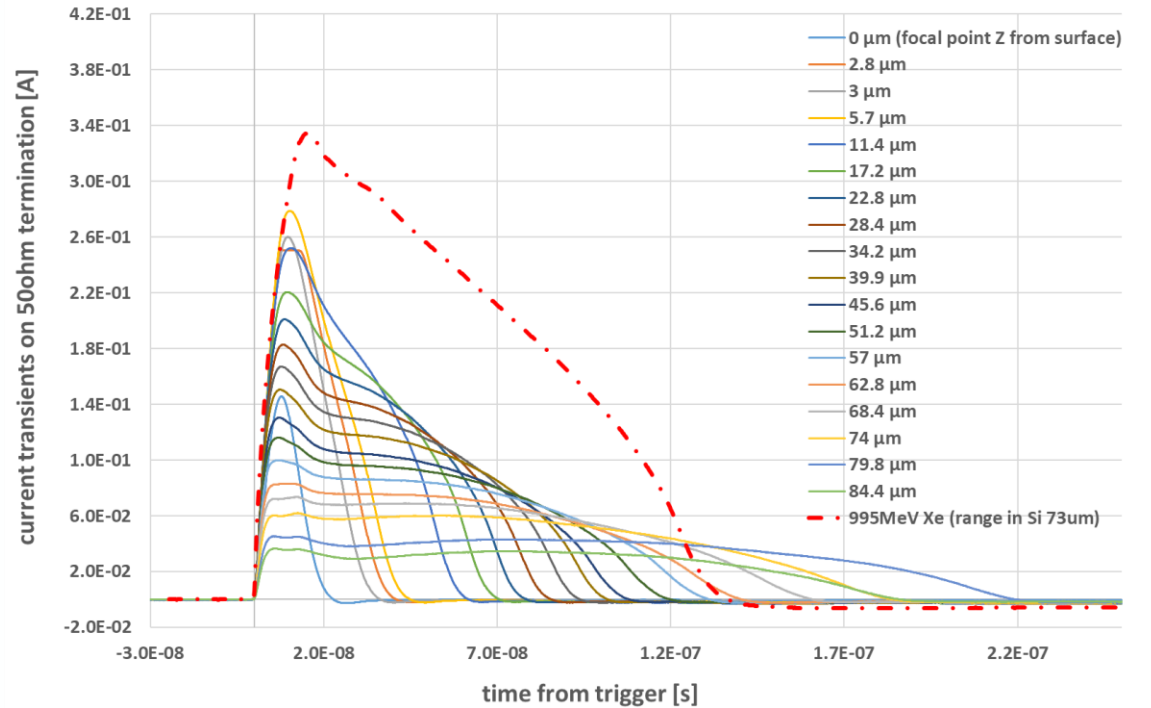
Measured pulses of the biasing voltage of the diode with depth in the diode



# Pin Diode – Photo diode



Charge collection profiles from a fully depleted 300um PiPS diode with TPA beam at different focal distances from the detector surface



Minority carriers takes more time to travel to the negative pole

## Result:

- Shape can help determining z position of generation
- Could be used to determine location of Brag Peak
- Ion signature

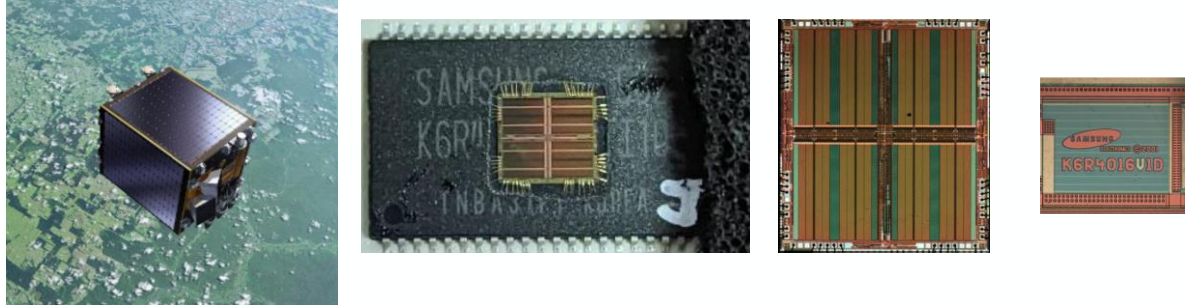
# Comparison Heavy Ion / Laser

Case of an SRAM - Samsung 4Mbit K6R4016V1C



# SRAM – Samsung 4Mbit K6R4016V1C

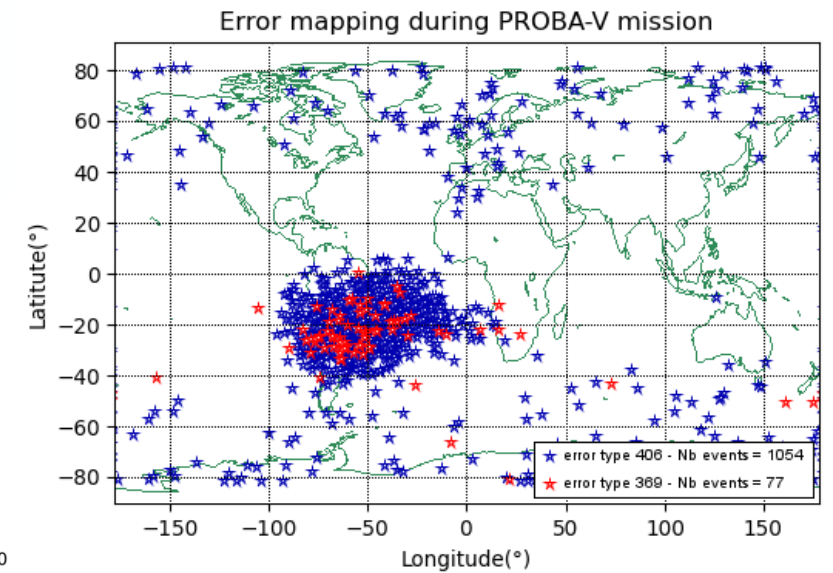
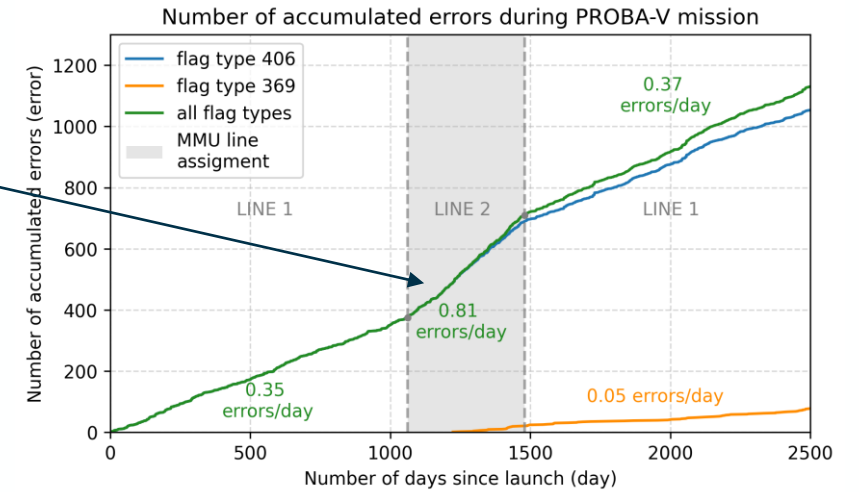
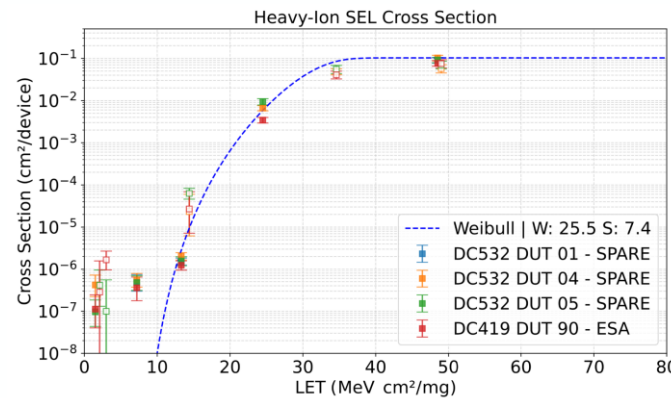
**DUT:** K6R4016V1C-TI10 with a die SEL sensitive



**Goal:** Internal investigation to understand the cause(s) of the ~1 year average SEL error rate during operations

**Study:**

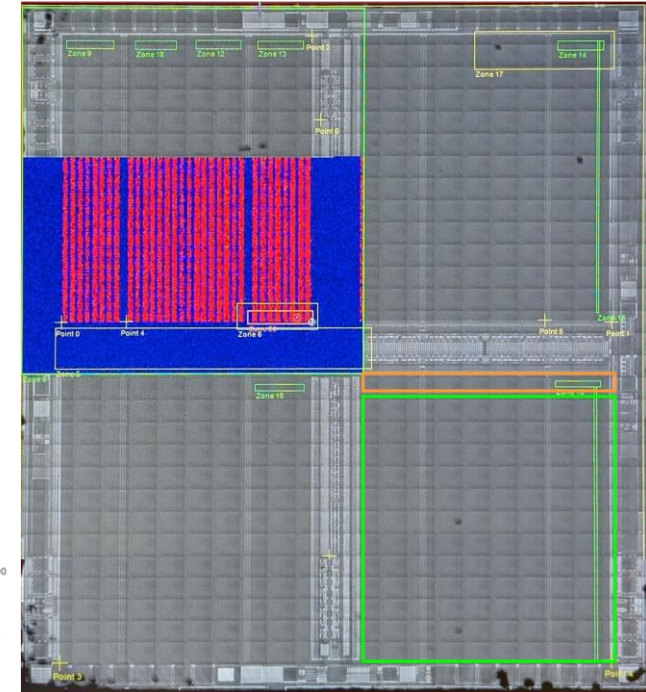
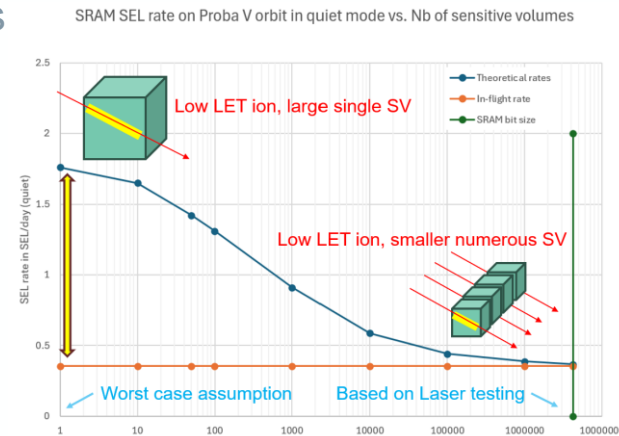
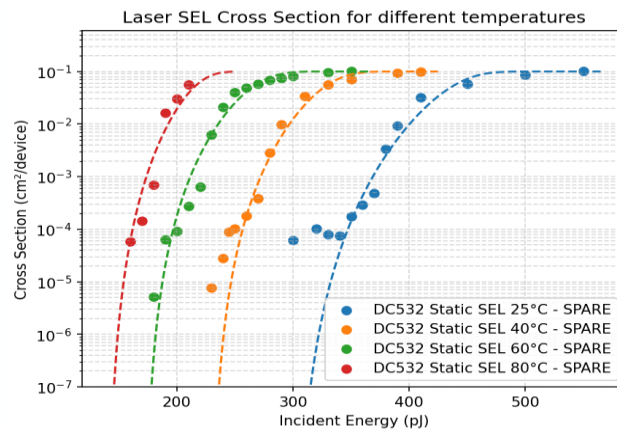
- Heavy-ion data showed that part-to-part variability (from flight “lot”) cannot explain this increase
- Alternative causes could be:
  - Temperature – not assessed during heavy-ion testing
  - Shielding difference between main & redundant unit
- Also unexpected increase of XS at low LET



# SRAM – Samsung 4Mbit K6R4016V1C

Laser testing was useful in this study to:

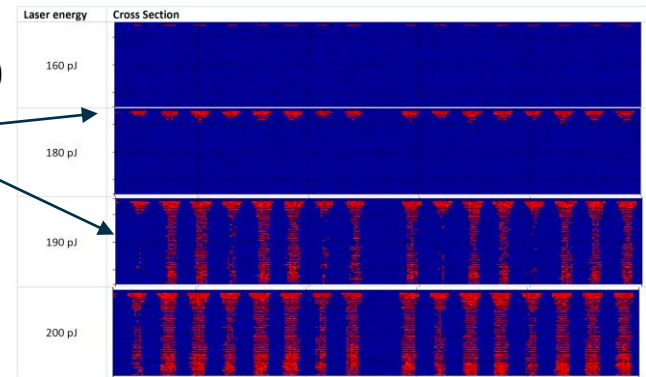
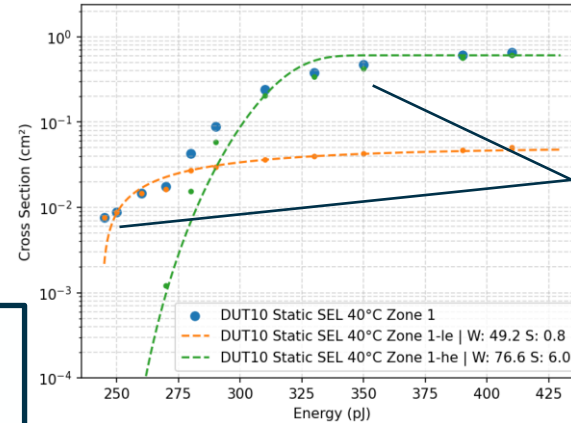
1. Confirm the assumption of a large number of Sensitive Volumes to match in-flight error rate with theoretical calculations
2. Investigate SRAM SEL sensitivity with temperature



3. Provide more insights into the possible cause of the low LET cross-section behaviour: areas near the central periphery appear at lower LET & quickly saturates: perhaps another parasite path?

Laser tests here allowed to deepened investigations easily (low cost) & complement heavy-ion data

Laser SEL Cross Section Comparison between Lower and Higher Energy Effects





# Comparison Heavy Ion / Laser

Case of a Voltage Reference – SET Worst Case on TL1431



# SET worst case - TL1431

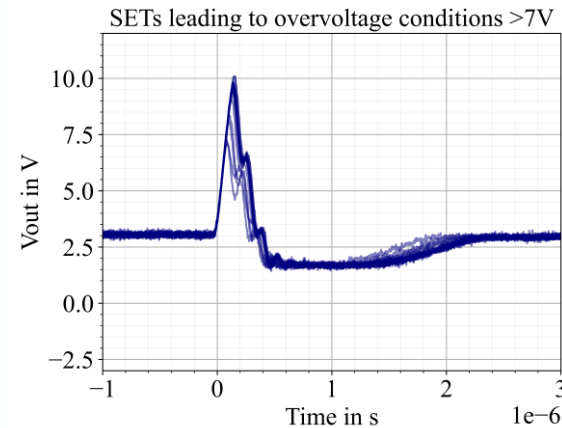
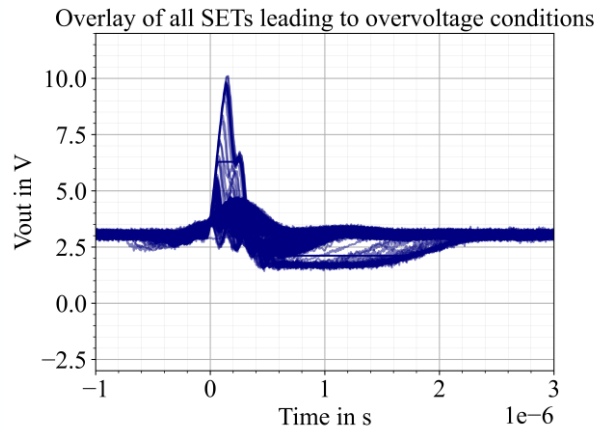
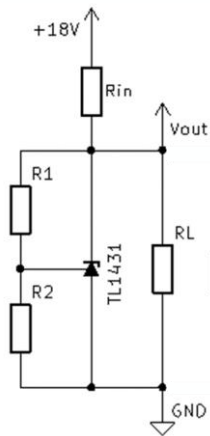
## DUT: Voltage Reference – TL1431-SP

### Objective:

- Crosscheck some data on the maximum duration of an SET
- Verification with Laser, then with HI

### Results with Heavy Ion:

- HI tests performed to obtain the WC transient (Xe: LET 62.5 MeV.cm<sup>2</sup>.mg<sup>-1</sup>)



- WC Transient: 10V and ~2μs

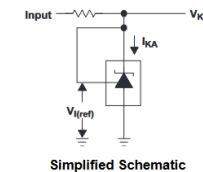
### TL1431-SP Class V, Precision Programmable Reference

#### 1 Features

- QMLV qualified to 100-krad(Si) RHA, 5962R99620
- 0.4% initial voltage tolerance
- 0.2-Ω typical output impedance
- Fast turnon: 500 ns
- Sink current capability: 1 mA to 100 mA
- Low reference current (REF)
- Adjustable output voltage:  $V_{I(REF)}$  to 36 V

#### 2 Applications

- Adjustable voltage and current referencing
- Secondary side regulation in flyback SMPSs
- Zener replacement
- Voltage monitoring
- Comparator with integrated reference
- Command and data handling (C&DH)
- Optical imaging payload
- Radar imaging payload
- Satellite electrical power system (EPS)



#### 3 Description

The TL1431 is a precision programmable reference with specified thermal stability over automotive, commercial, and military temperature ranges. The output voltage can be set to any value between  $V_{I(REF)}$  (approximately 2.5 V) and 36 V with two external resistors. This device has a typical output impedance of 0.2 Ω. Active output circuitry provides a very sharp turnon characteristic, making the device an excellent replacement for Zener diodes and other types of references in applications such as onboard regulation, adjustable power supplies, and switching power supplies.

The TL1431 is characterized for operation over the full military temperature range of -55°C to 125°C.

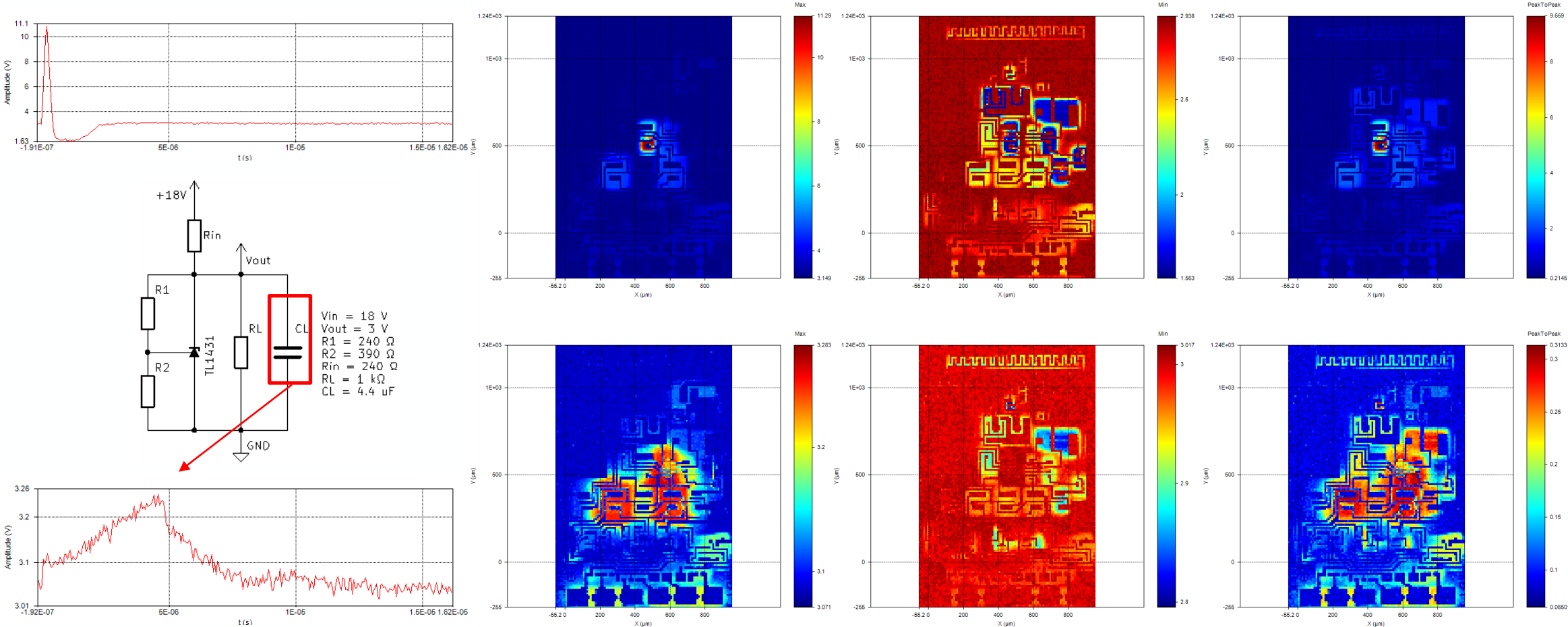
#### Device Information

PART NUMBER <sup>(1)</sup>	GRADE	PACKAGE
5962R9962001VPA	Flight grade RHA 100 krad(Si)	8-pin JG Weight 0.87 g <sup>(2)</sup>
5962-9962001VPA	Flight grade class V	
5962R9962001VHA	Flight grade RHA 100 krad(Si)	10-pin U Weight 0.2 g <sup>(2)</sup>
TL1431U/EM	Engineering samples <sup>(3)</sup>	EVM

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) Weight is accurate to ±10%.
- (3) These units are intended for engineering evaluation only. They are processed to a noncompliant flow (that is, no burn in, and so forth) and are tested to a temperature rating of 25°C only. These units are not suitable for qualification, production, radiation testing or flight use. Parts are not warranted for performance over the full MIL specified temperature range of -55°C to 125°C or operating life.

# SET worst case SET. TL1431

## Results with Laser:



# Failure analysis

Case of a Point of Load



**DUT:** Point of Load

**Operator:** Marta Rizzo

**Background:**

- Developed in a frame of an ESA activity → POL-RH
- HI test showed a sensitivity to SEFI and SEB at high load

**Objective:**

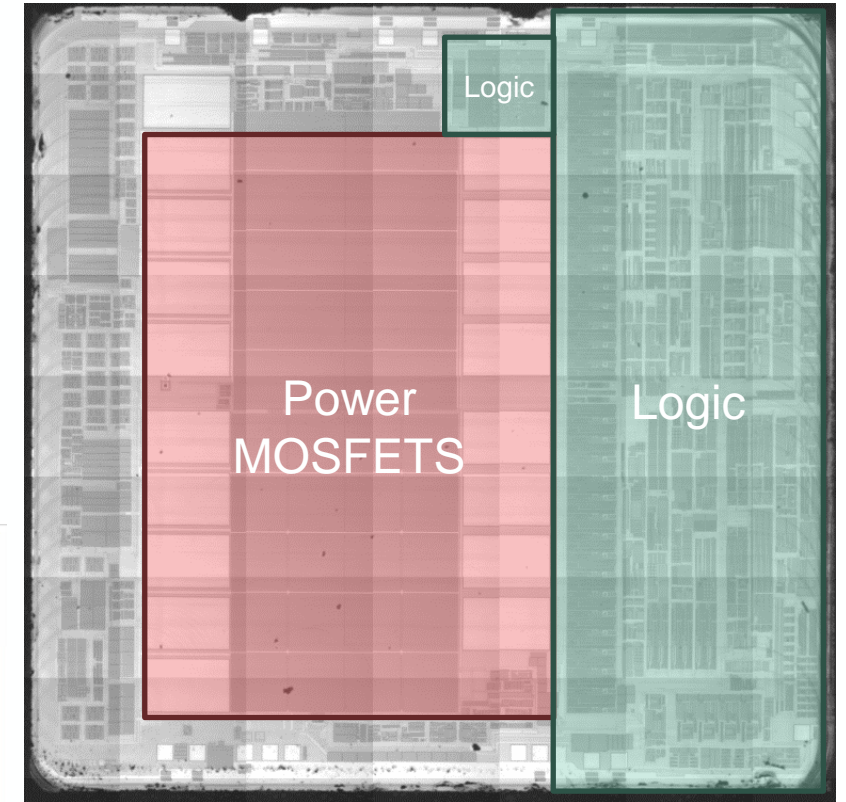
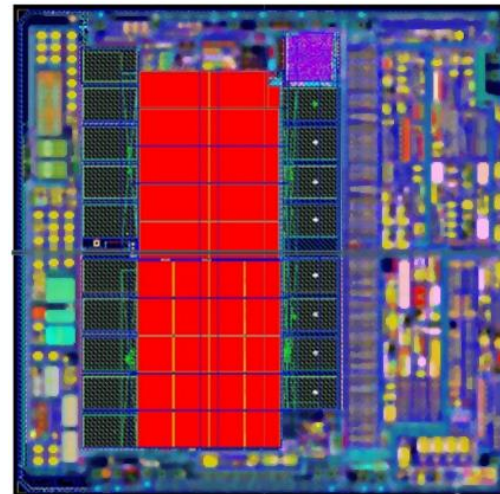
- Detect the SEFI sensitivity region
- Detect SEB sensitivity area

**Material:**

- Design layout
- Contact with Manufacturer

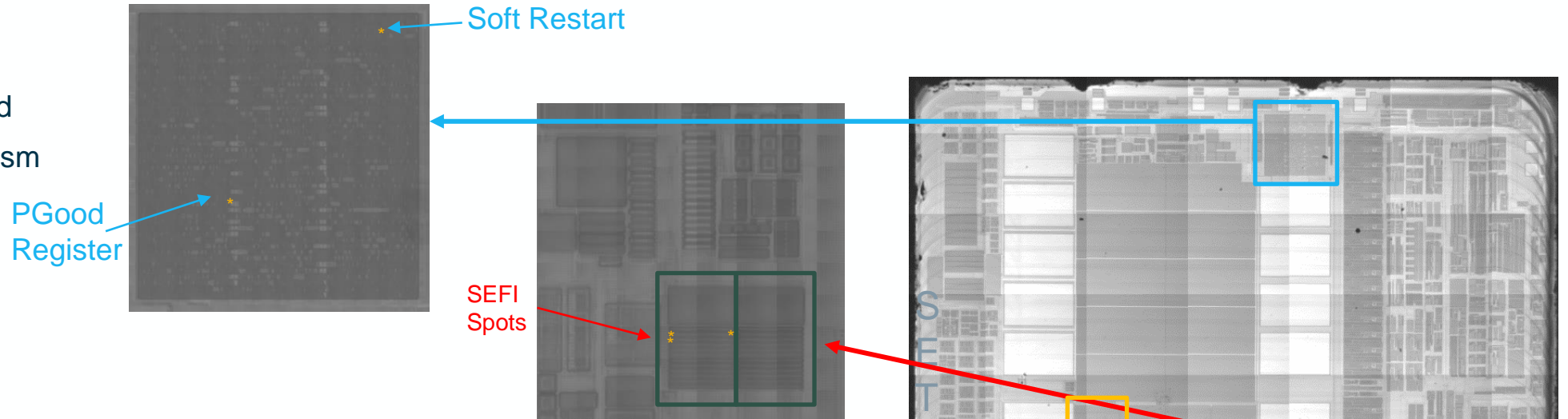
**Suspects:**

- None



## SEFI:

- Several SEFI spot located
- Different Failure mechanism
- Trigger repeatable



## SEB:

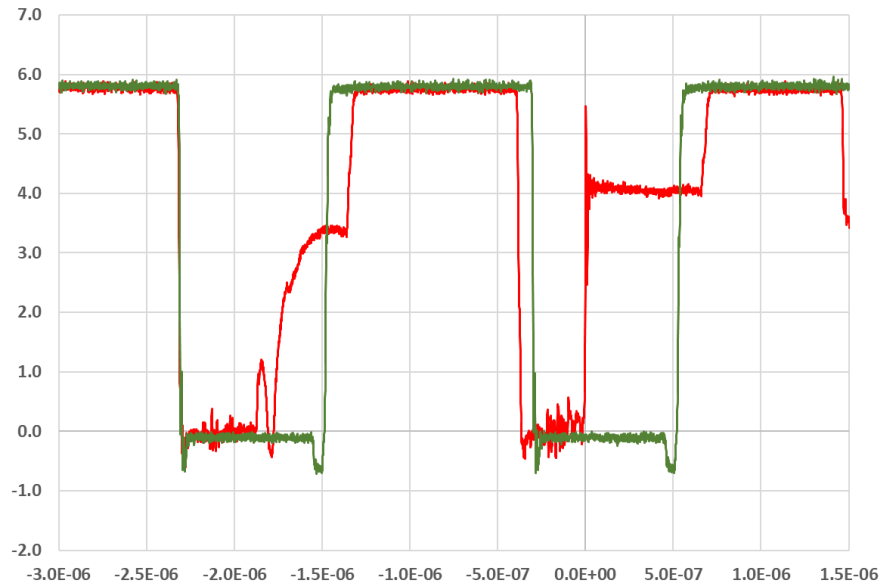
- Sensitive area detected
- Event Triggered with several DUT
- SPA and TPA used
- Failure mechanism same as HI tests



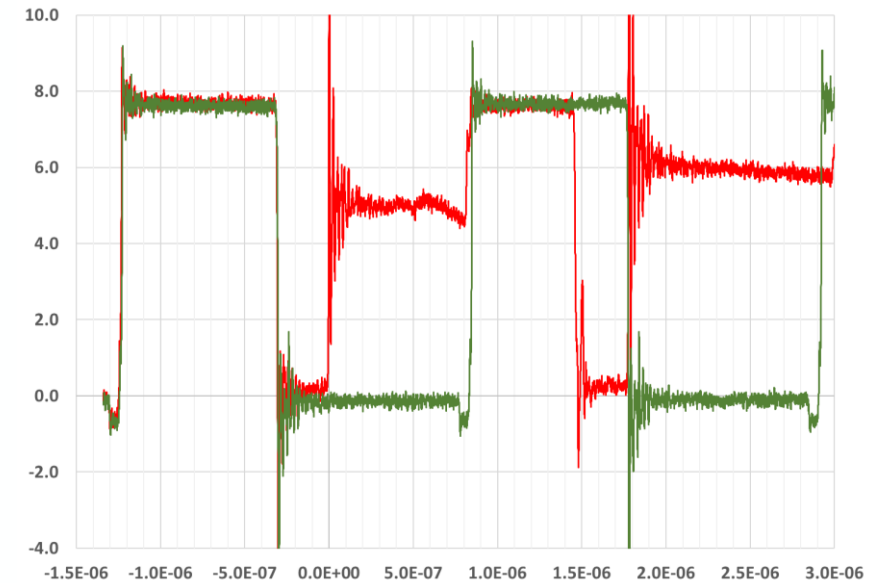
POWER High Side

## Failure mode of PoL Output Power MOSFET's

Output waveforms before filtering



**995MeV  $^{124}\text{Xe}^{35+}$  Heavy Ion beam**  
(LET 62 MeV/mg/cm<sup>2</sup> LET)



**SPA 1064nm Laser 1nJ**

**Burn-out triggered**

# Fault Injection

Case of an STM32





DUT: STM32F407

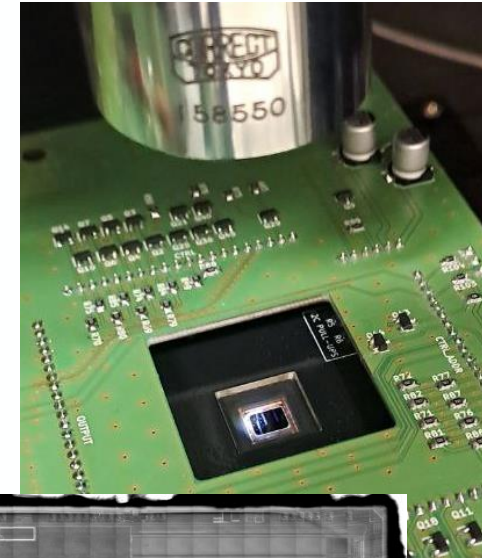
Operator: Federico Reghenzani (Politecnico di Milano, IT)

## Objective:

- **Software-Implemented Hardware Fault Tolerance (SIHFT)** techniques via laser-based SEU injection
- Test the capability of SIHFT techniques to detect and recover from SEUs by injecting faults without breaking timing metrics

## Experimental results:

- COTS automotive **STM32** microcontroller running FreeRTOS with some benchmarks
- The results are promising and showed that when SIHFT is employed, **less than 0.05%** of the effective faults result in a **Silent Data Corruption (SDC)** compared to an unprotected version that exhibits 30%-99% SDC rate (depending on the benchmark)



Die of the STM32F407

# Conclusion



## Non-Routine test cases presented:

- Comparison SEE Laser vs Heavy Ions
  - Pin diode: Mechanism understood, more tests to be performed
  - SRAM: allowed to deepened investigations on SEL sensitivity & complement heavy-ion data
  - Voltage Reference: Worst-Case SET found, and other configurations tested
- Failure Analysis:
  - Point of Load: Localisation of SEFI and SEB and underwent redesign
- Fault Injection
  - $\mu$ P STM32: Positive results on the SHIFT technics tested with laser